

# Novel rear structure design for an effective optical enhancement in ultrathin Cu(In,Ga)Se<sub>2</sub> solar cells

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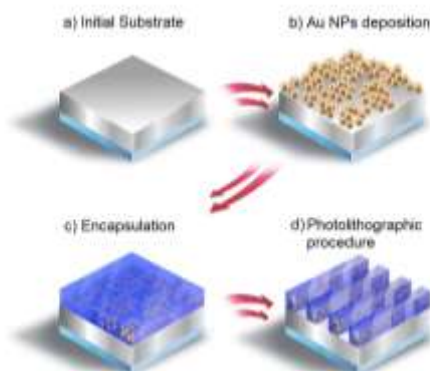
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Amongst all the thin film solar cells technologies, Cu(In,Ga)Se<sub>2</sub> solar cells stand out, due to presenting the foremost power conversion efficiency value (23.35 %), and for satisfying the requirement for new application possibilities imposed by the photovoltaic industry [1]. Nonetheless, sub- $\mu\text{m}$  ultrathin solar cell absorbers have been gaining relevance, as they allow to meet economic and technological targets through cost-reduction objectives [2]. However, the thickness reduction comes with drawbacks, such as, a decreased light absorption and increased interface recombination. To tackle the imposed downsides, light management as well as interfacial passivation strategies need to be employed. In this work, a novel light management architecture is used to enhance the optical path in the absorber. Gold nanoparticles (NPs) aggregates were integrated at the solar cell rear contact and encapsulated with a dielectric matrix commonly used as a passivation layer in solar cells. The rear substrate fabrication procedure is represented in **Figure 1**. This way, an encapsulation strategy shielding the fabricated nanostructures from the high temperatures and harsh processing conditions of the remaining device is coupled with a passivation approach to reduce rear interface recombination. An X-ray photoelectron spectroscopy analysis was conducted demonstrating the effective encapsulation of the Au nanostructures. With the novel rear architecture, a broadband external quantum efficiency increase was obtained, leading to a 17.4 % increase of the short circuit current density value over a reference device.

## REFERENCES

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## FIGURES



**Figure 1:** Schematic illustration rear structure fabrication. a) Initial substrate. b) Au NPs deposition. c) Au NPs encapsulation with a 25 nm Al<sub>2</sub>O<sub>3</sub> layer. d) Photolithographic procedure allowing for an electrical contact. Taken from [3].